



- NOTES:
- 1.MATERIAL:HOUSING---LCP 30% GLASS FILL
UL94 V-0,COLOR BLACK
TERMINAL---PHOSPHOR BRONZE 0.12MM REF THICKNESS
 - 2.PLATING:TERMINAL:SIM SIDE---0.8 MICROMETER MIN GOLD
SOLDER TAIL---GOLD FLASH 0.05 MICROMETER MIN
UNDERPLATING---2 MICROMETER NICKEL OVERALL
 - 3.NO SHARP EDGES INTERFACING WITH THE PCB OR SIM CARD
 - 4 CONTACT MUST NOT EXTENDED BEYOND HOUSING EDGE DURING DEFLECTION AND MUST LOWER THAN HOUSING LEVEL AFTER 3TIMES REFLOW
 - 5 MAINTAIN IN CONTACT AREA
 - 6 THIS IS LEAD FREE PRODUCT

| | | | | | | | | | | |
|--|--------------------|--------------------------------|---------------------------------------|--|----------------------------|---|--------------------------------------|------------------------|--|--|
| NEW PRODUCT EC NO: DRWN:CYZHU CHKD:XIXU APPR: A | DESCRIPTION REV | QUALITY SYMBOLS ▽=0 ▽C=2 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE 5:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | | mm | INCH | DRAWN BY CYZHU | DATE 2006/08/31 | TITLE 8 CKT MEGA SIM CONNECTOR | | | |
| | | | 4 PLACES ± --- | ± --- | APPROVED BY | DATE | MOLEX INCORPORATED | | | |
| | | | 3 PLACES ± --- | ± --- | MATERIAL NO. 474940001 | DOCUMENT NO. SD-47494-001 | SHEET NO. 1 OF 1 | | | |
| | | 2 PLACES ± 0.15 | ± --- | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |
| | | 1 PLACE ± 0.2 | ± --- | | | | | | | |
| | | ANGULAR ± 2 ° | | | | | | | | |